
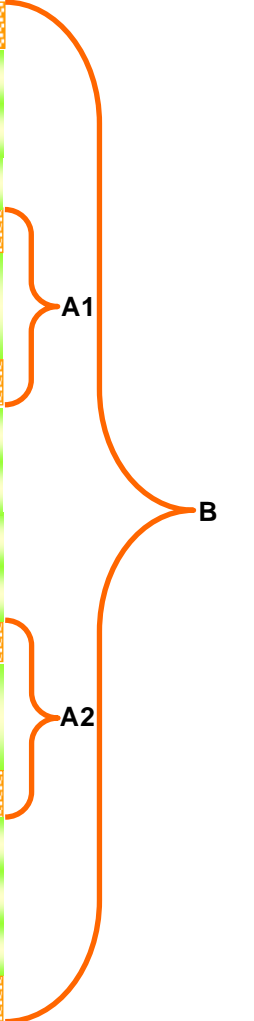

















Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
06	323	FR4	55	L71.35	P10_18	S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_323_FR4_55_L71.35_p10_18_s1

Layers	in μ	Material	Build-Up	Assembly
Layer-1	55 μ	Copper		
	100 μ	Prepreg	(100 μ PrePreg-Type: 2125)	
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-2	35 μ	Copper		
	710 μ	L-FR4		
Layer-3	35 μ	Copper		
	180 μ	Prepreg	(180 μ PrePreg-Type: 7628)	
	180 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-4	35 μ	Copper		
	710 μ	L-FR4		
Layer-5	35 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-99	55 μ	Copper		

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